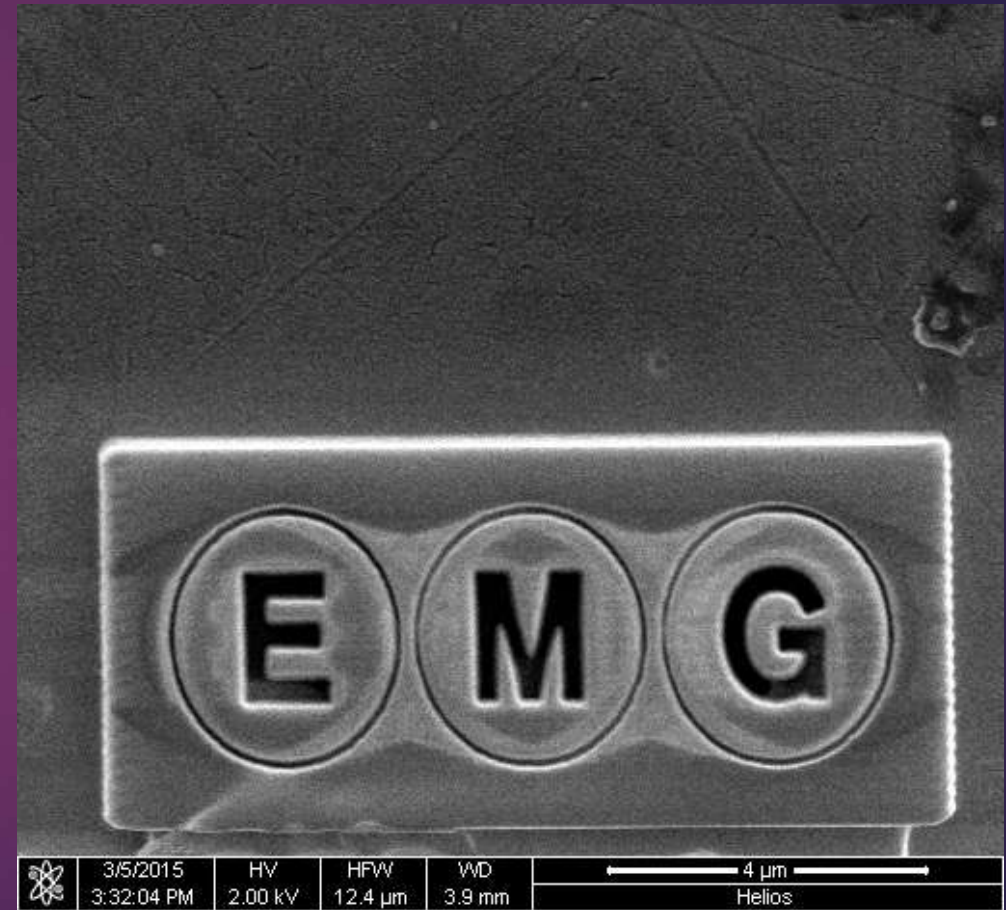


FIB SEM

TOMOGRAPHY SHORT COURSE

APRIL 2021

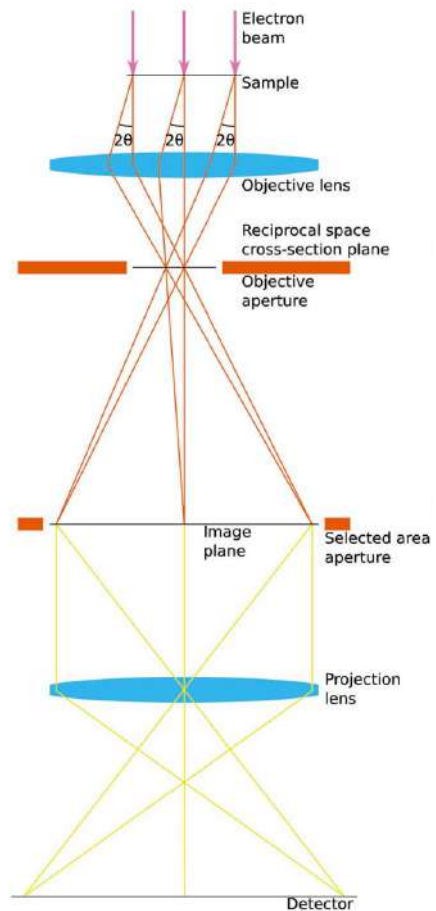
WILLIAM RICE, NYU SCHOOL OF MEDICINE



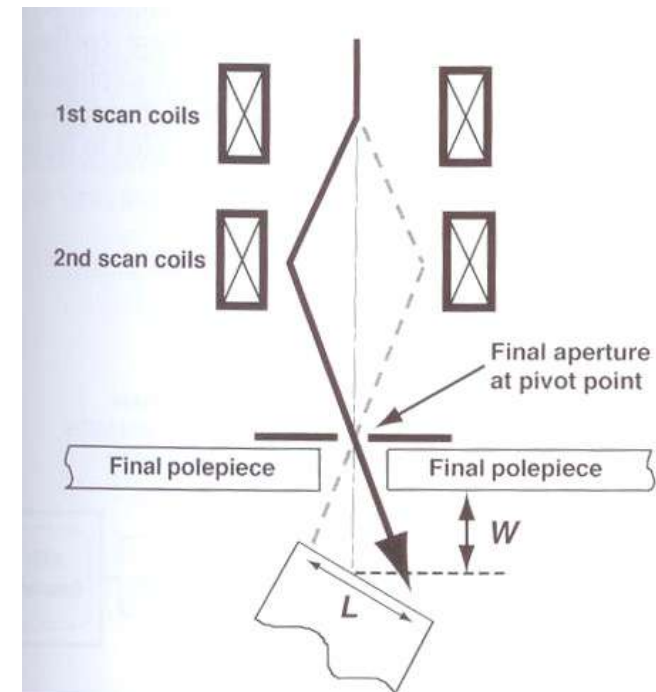
SEM Basics

SEM versus TEM

TEM

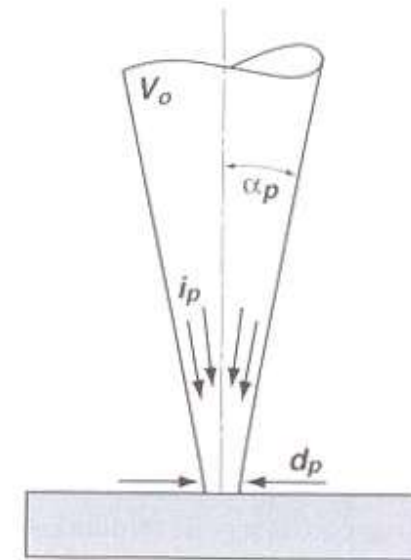


SEM



SEM Beam: probe size

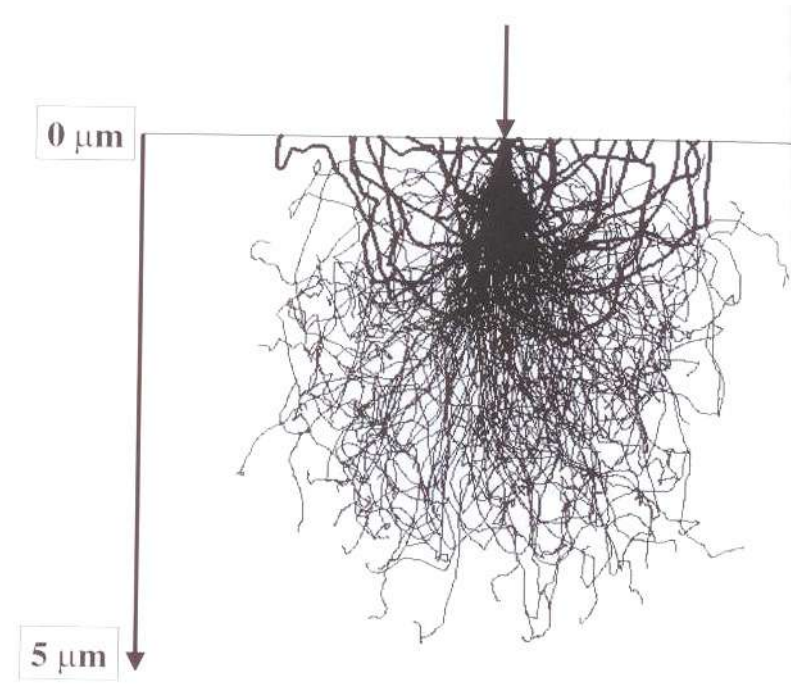
- ◆ Ideally want as small a probe as possible, relative to pixel size
- ◆ Probe size is determined by voltage, current, divergence angle
- ◆ Lens distortions
 - ◆ Spherical aberration (focus different at center and edge of lens) – proportional to focal length (working distance)
 - ◆ Aperture diffraction
 - ◆ Astigmatism (user correctable)
 - ◆ Chromatic aberration – voltage dependent (higher at low voltage)



Goldstein et al, 2003

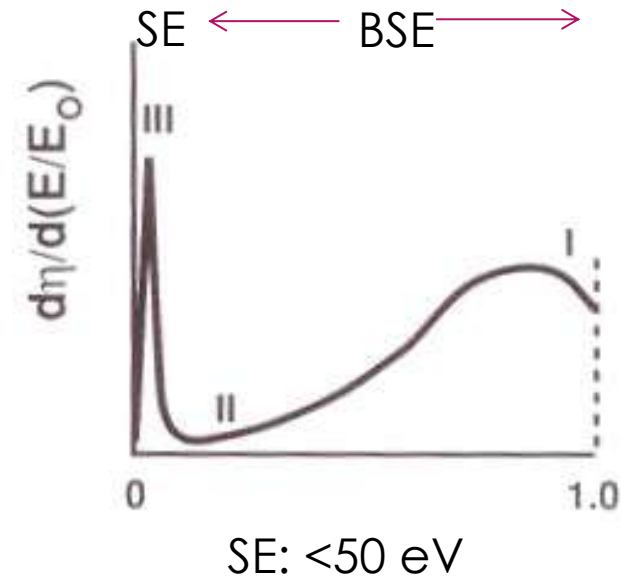
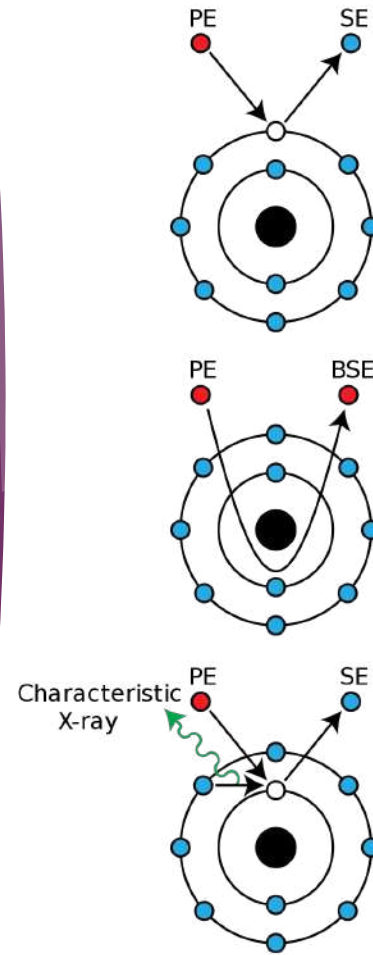
Beam-Specimen Interaction

- Monte Carlo simulation of a 20 keV beam in Si
 - Dark traces: electrons which left the sample (BSE's)
- Electrons may be scattered elastically or inelastically
- Probability of elastic scattering $\sim Z^2$
- Inelastic scattering:
 - Secondary electrons
 - X-rays

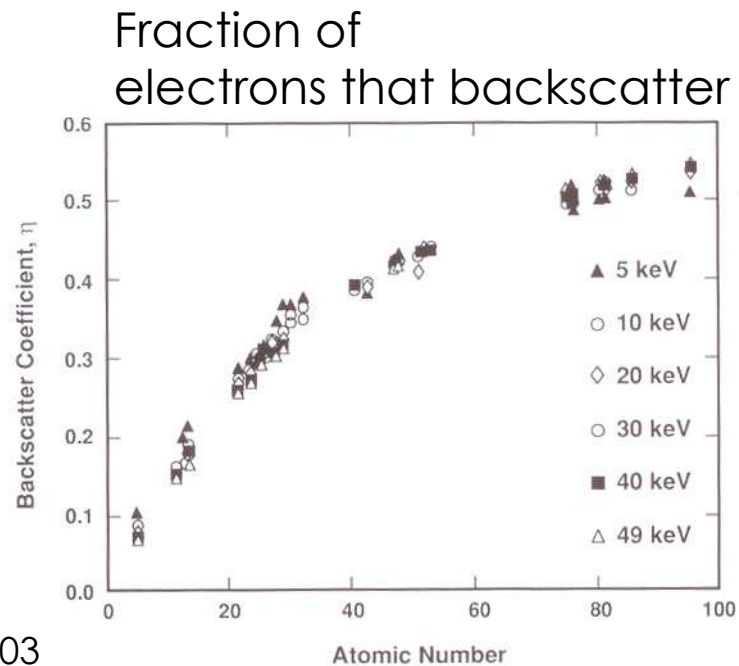


Goldstein et al, 2003

Signal: Back Scattered Electrons (BSE's) and Secondary Electrons (SE's)

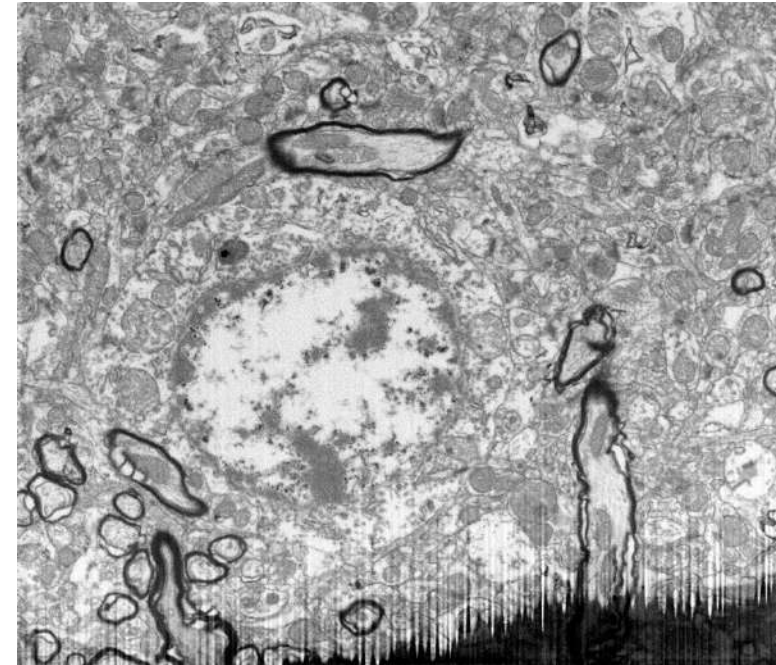


BSE efficiency is material dependent, voltage independent



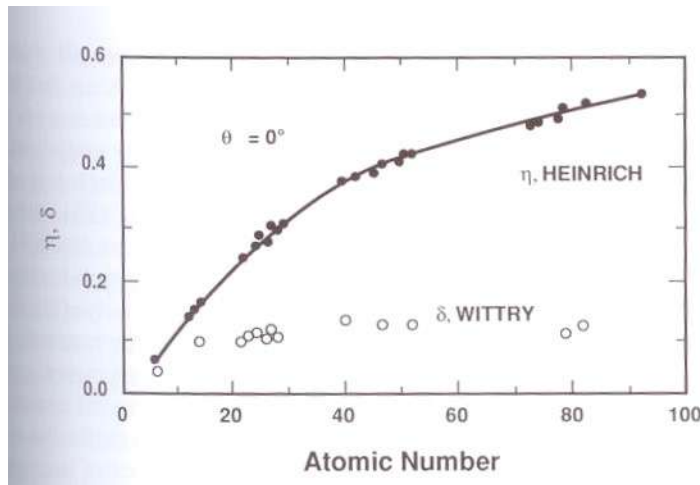
Goldstein et al, 2003

BSE's give contrast
between light and
heavy elements



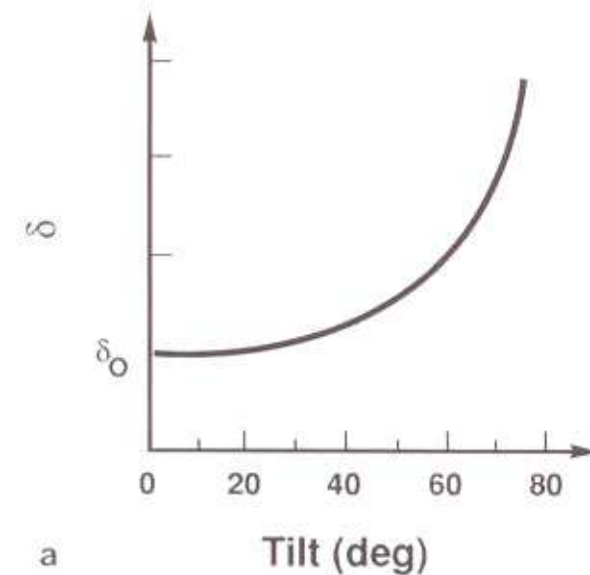
Osmium stained, resin-embedded tissue

Secondary Electrons are much less sensitive to element difference, more sensitive to topographic information



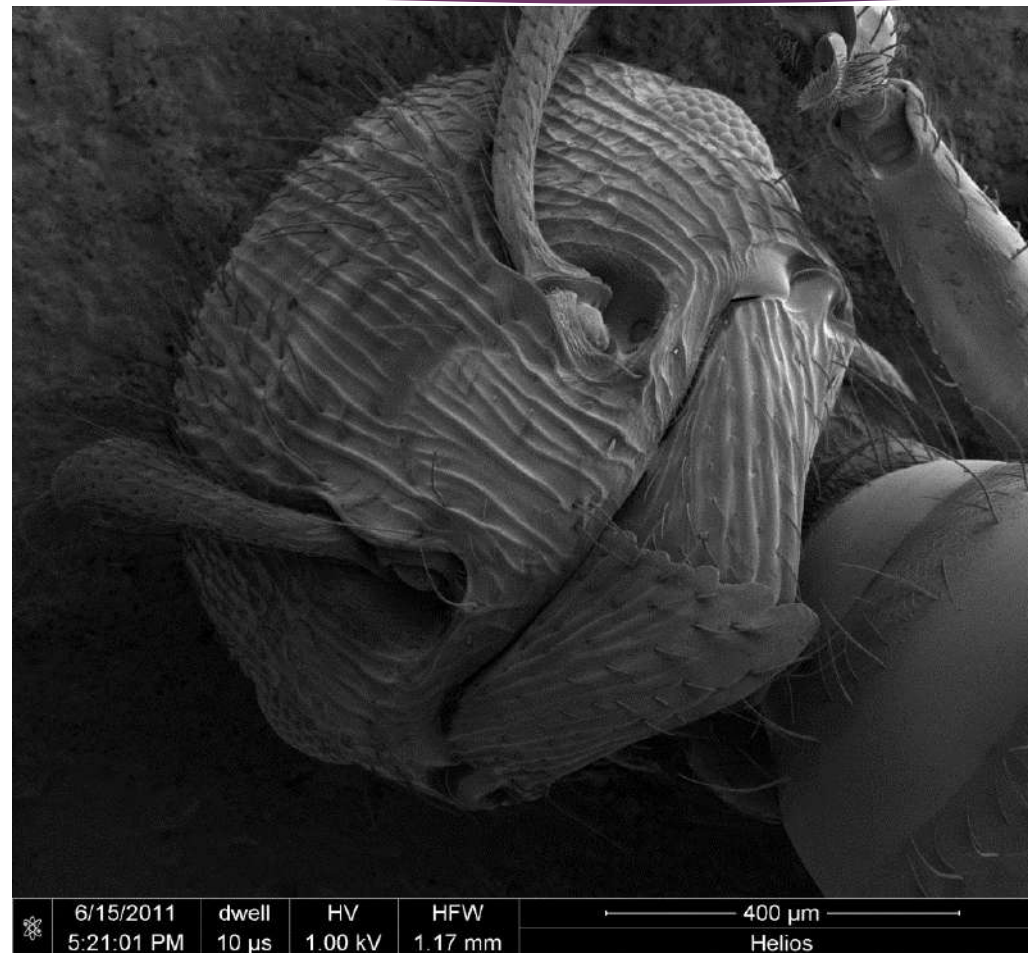
30 keV

SE's are less sensitive to atomic number than BSE's (may be more sensitive at lower beam energies)

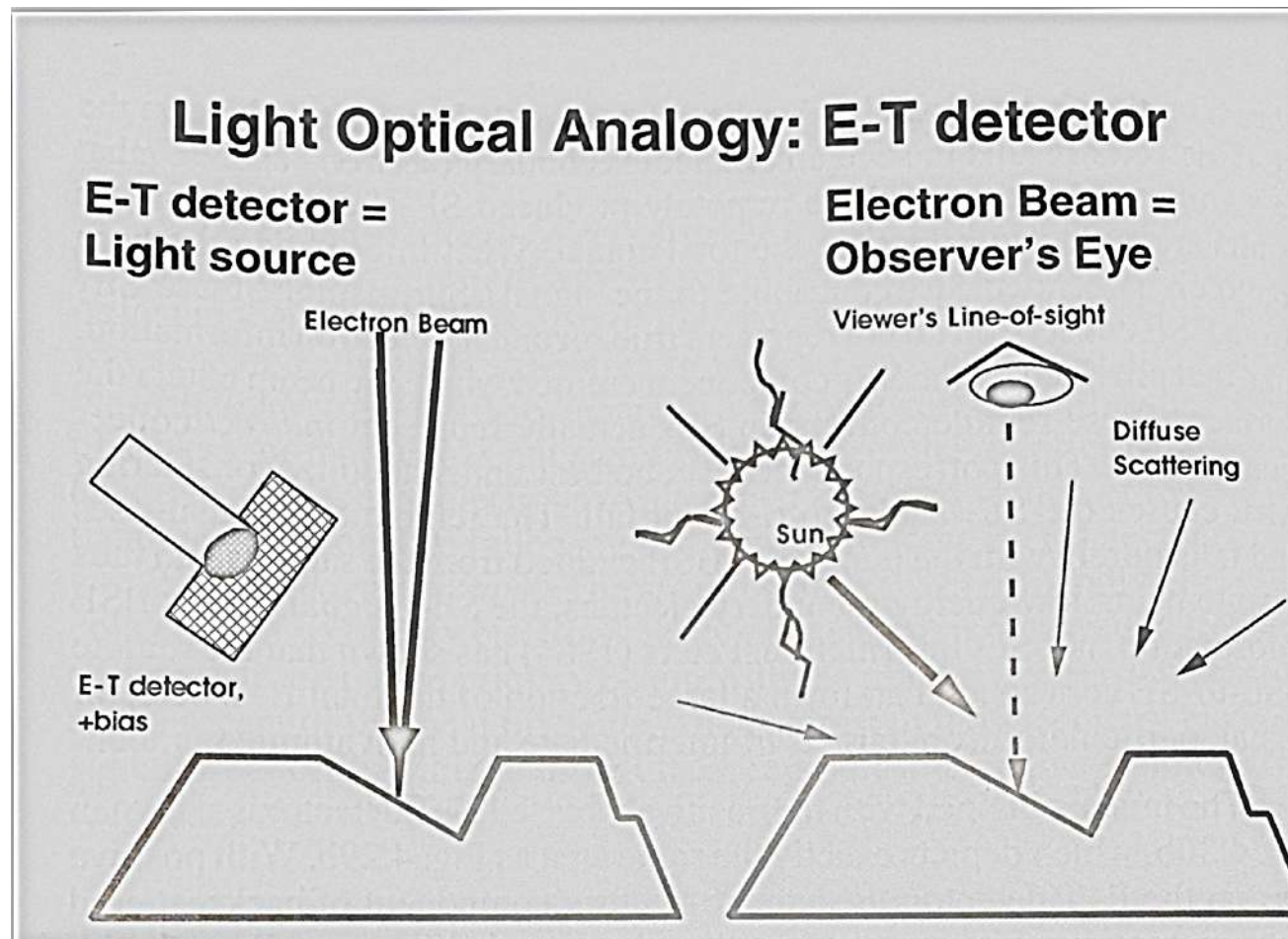


Signal is strongly dependent on viewing direction

SE's give excellent topographic information



Light-optical analogy



Non-conductive samples

- ▶ Imaging with electrons on non-conductive samples is difficult due to charging artifacts
 - ▶ Resin-embedded samples, biological specimens, frozen samples
- ▶ Generally make them conductive beforehand by sputter-coating with metal (Pt, Au)
- ▶ Image using low voltage (5 keV or less) and low current
 - ▶ Current too low requires longer scan/integration times
- ▶ Ideally, the SEM includes a pre-loading chamber for sputter coating

SEM versus TEM

SEM

- ▶ Large chamber
 - ▶ Harder to reach highest vacuum
 - ▶ Many ports for add-ons
- ▶ Voltage: < 1 keV to 30 keV
 - ▶ Commonly <5 keV for non-conductive specimens
- ▶ Large samples of varying shape
- ▶ Signal from surface or just beneath surface
- ▶ Non-coherent imaging, no phase information

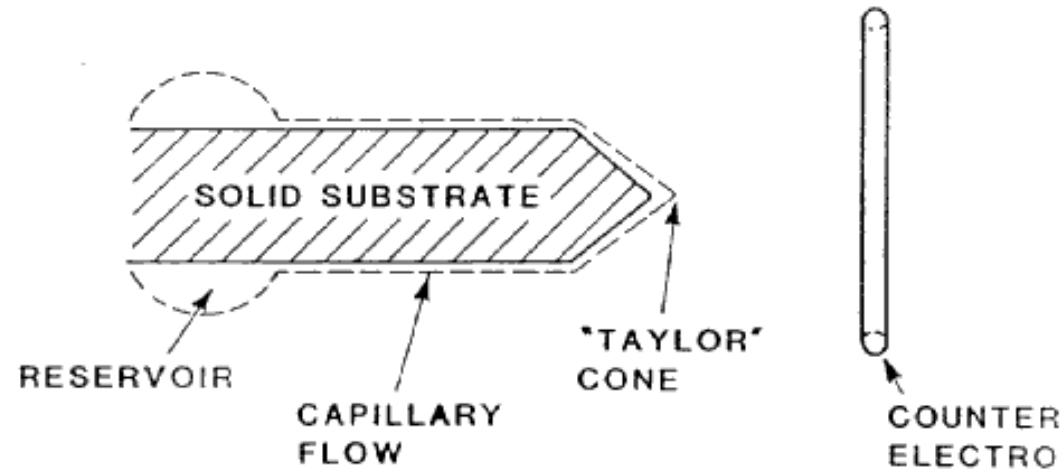
TEM

- ▶ Small Chamber
 - ▶ Easier to reach very high vacuum
 - ▶ Few ports for add-ons
- ▶ Voltage: 80-300 keV
 - ▶ 300 keV for highest resolution
- ▶ Thin samples (<500 nm) on TEM grid
- ▶ Projection images through sample
- ▶ Coherent beam imaging: phase preserved

FIB Operation

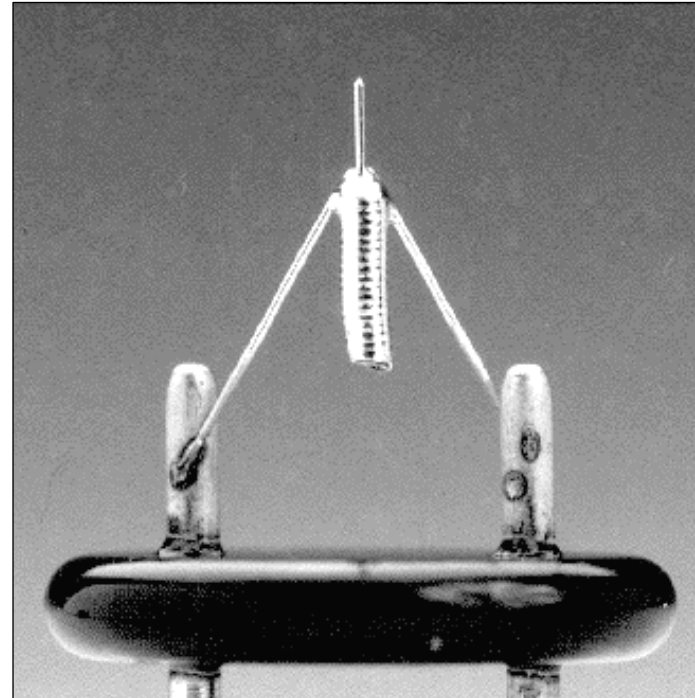
Basic Mechanism

- ◆ Liquid Flow from Reservoir
- ◆ Ion Formation
- ◆ External Beam Interactions



Gallium is the Most Popular LMIS

- ◆ A liquid metal
- ◆ Room temperature operation
- ◆ Long lived (500-1500 hr sources)
- ◆ High vacuum compatible
- ◆ Large ion for sputtering
- ◆ Other options
 - ◆ He, Ne, Xe
 - ◆ Mostly for materials sciences

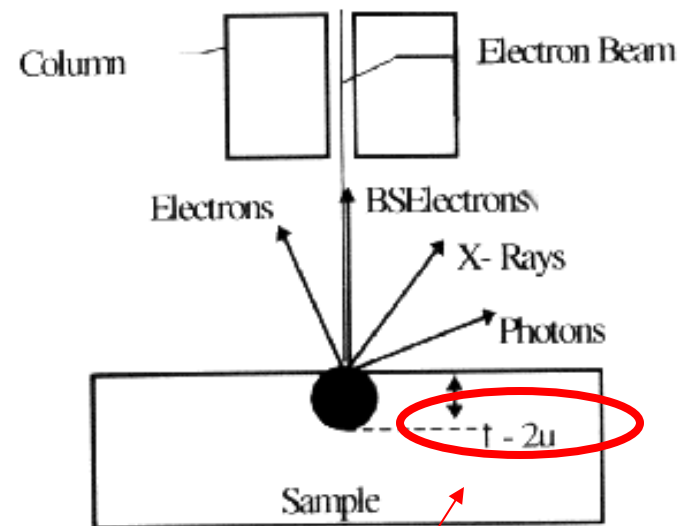
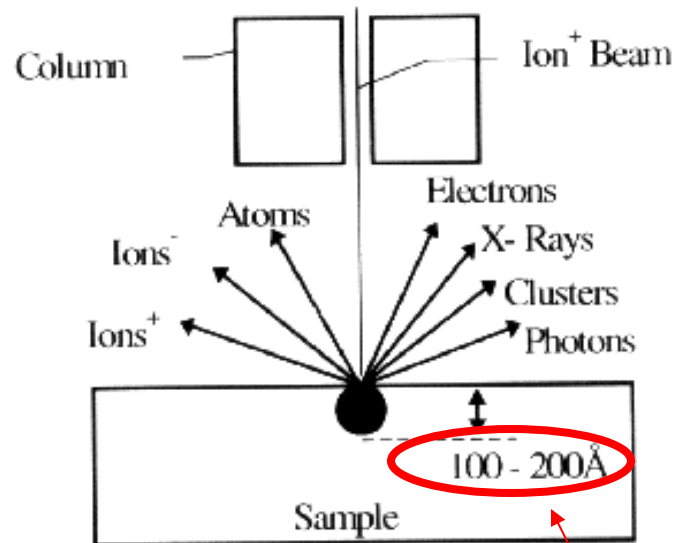


Ion Column

- ◆ Source - LMIS at top
- ◆ Focusing Optics
 - ▶ Use Electrostatic lenses since ions are heavier than electrons.
- ◆ Deflection Electronics/Pattern Board
- ◆ High-speed Blanking
 - ▶ Need to prevent milling while blanking
- ▶ Current is controlled by apertures
 - ▶ Apertures wear out over time and must be replaced!
- ▶ You can get images with FIB beam. Beam is much more damaging than electron beam so you need to image at as low current as possible
- ▶ Generally used at 30 keV, though voltage can be changed

Using the System

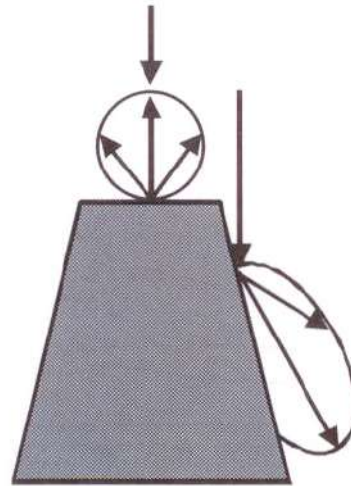
◆ Beam Interactions



Note difference in interaction volume

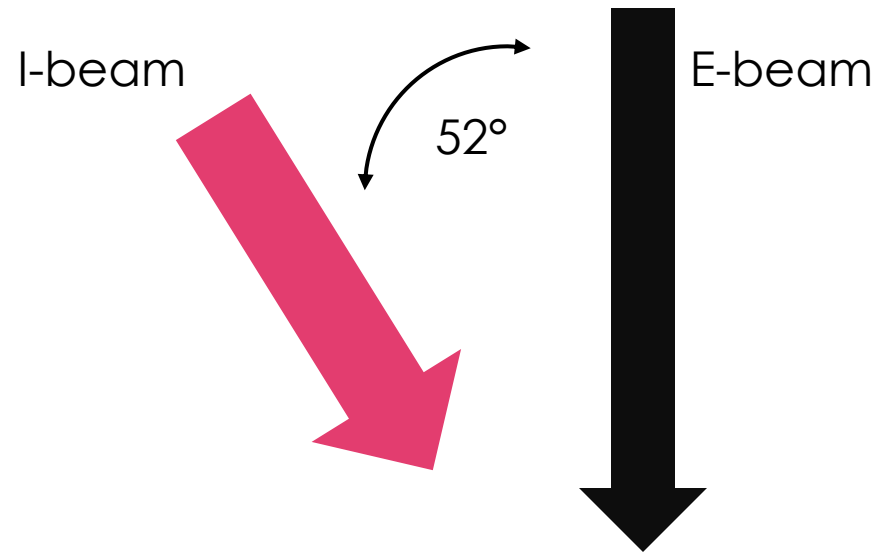
Common Use: Sputtering particles from substrate

Sputtered Particle Ejection Behavior



More efficient milling at edge than in bulk

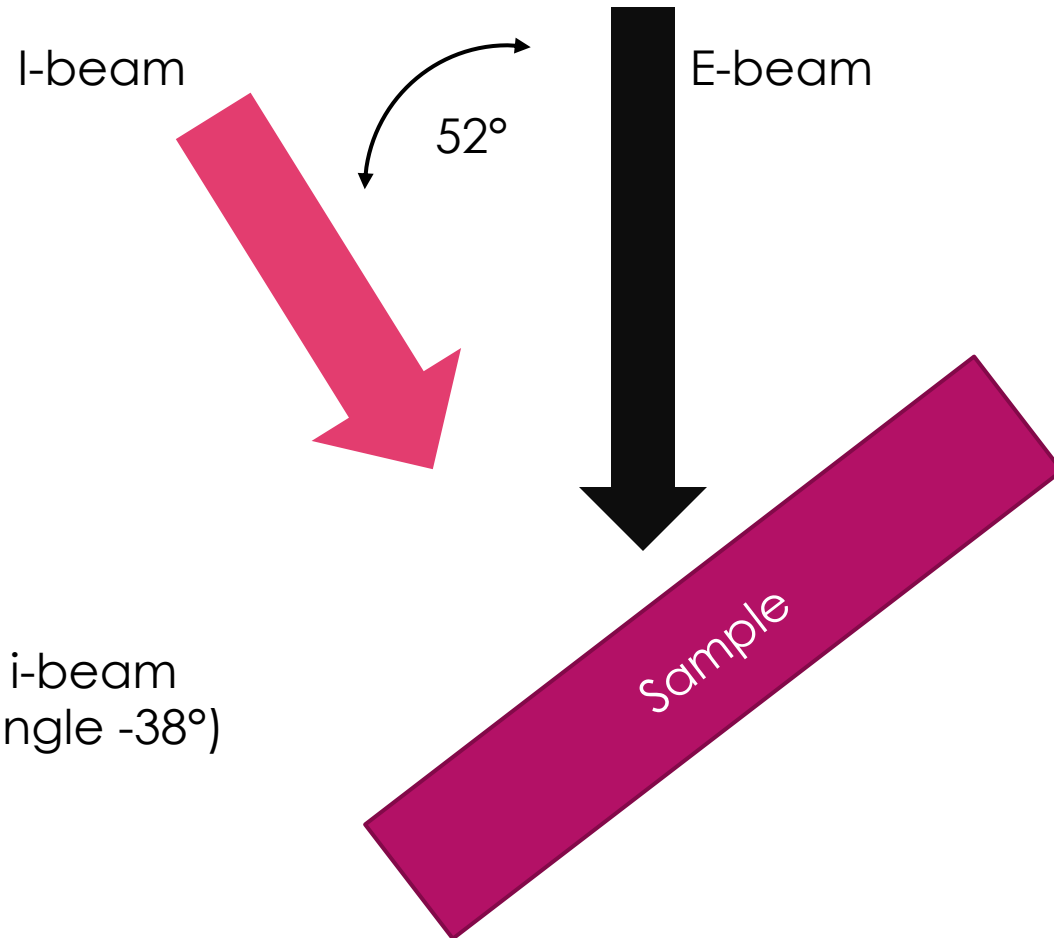
Geometry



Sample:
Tilt from -10° to $+70^\circ$

Sample

Geometry



Sample:

Tilt from -10° to $+70^\circ$

Tilt to 52° for orthogonal i-beam
(cross-section viewing angle -38°)

Geometry



Metal Deposition for surface protection (GIS)

- ▶ (Methylcyclopentadienyl) trimethyl platinum
- ▶ Warm to gas, spray over sample with needle
- ▶ I-beam or e-beam interactions break it apart, deposit metal onto sample
 - ▶ Protection
 - ▶ Hard surface for mill
 - ▶ Prevents “curtaining”

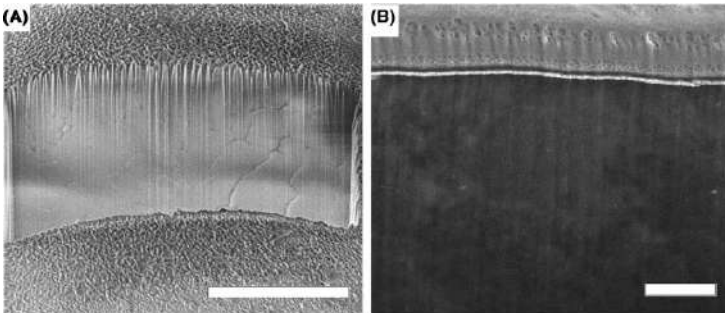
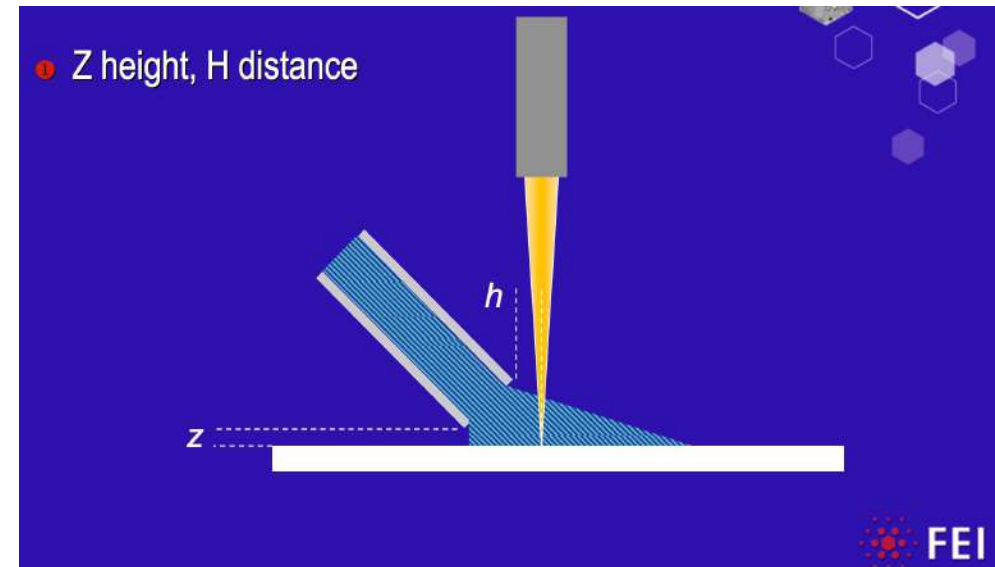
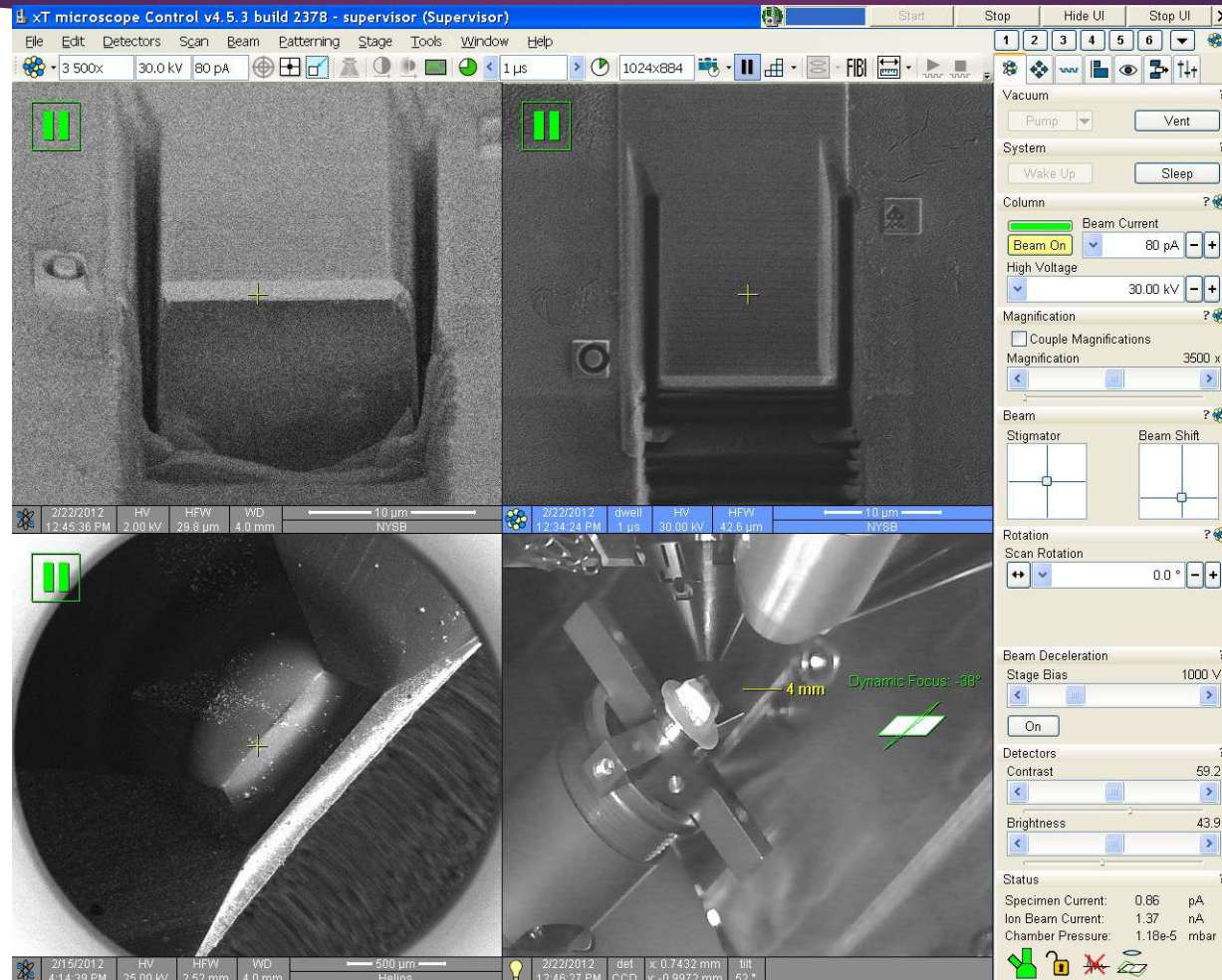


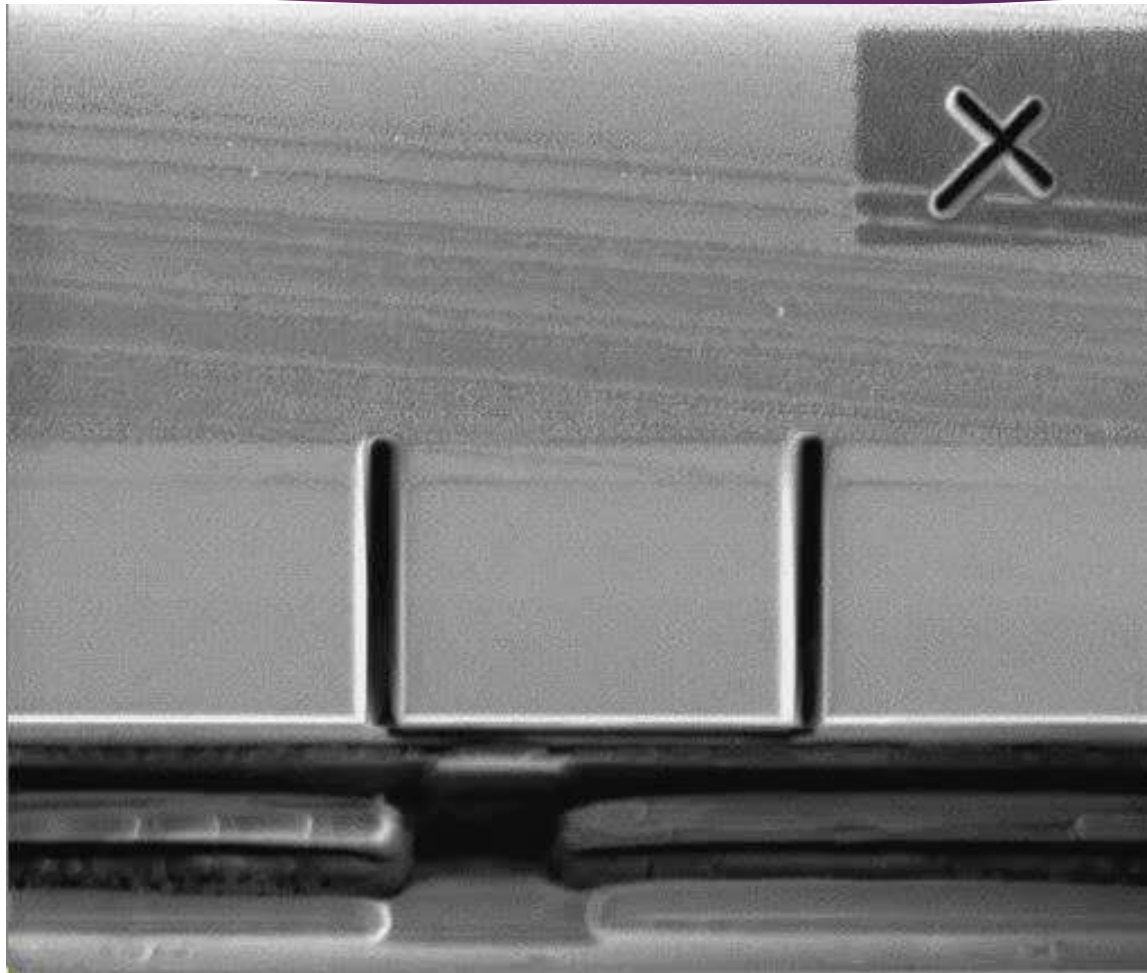
Image: Hayles and Winter, 2021



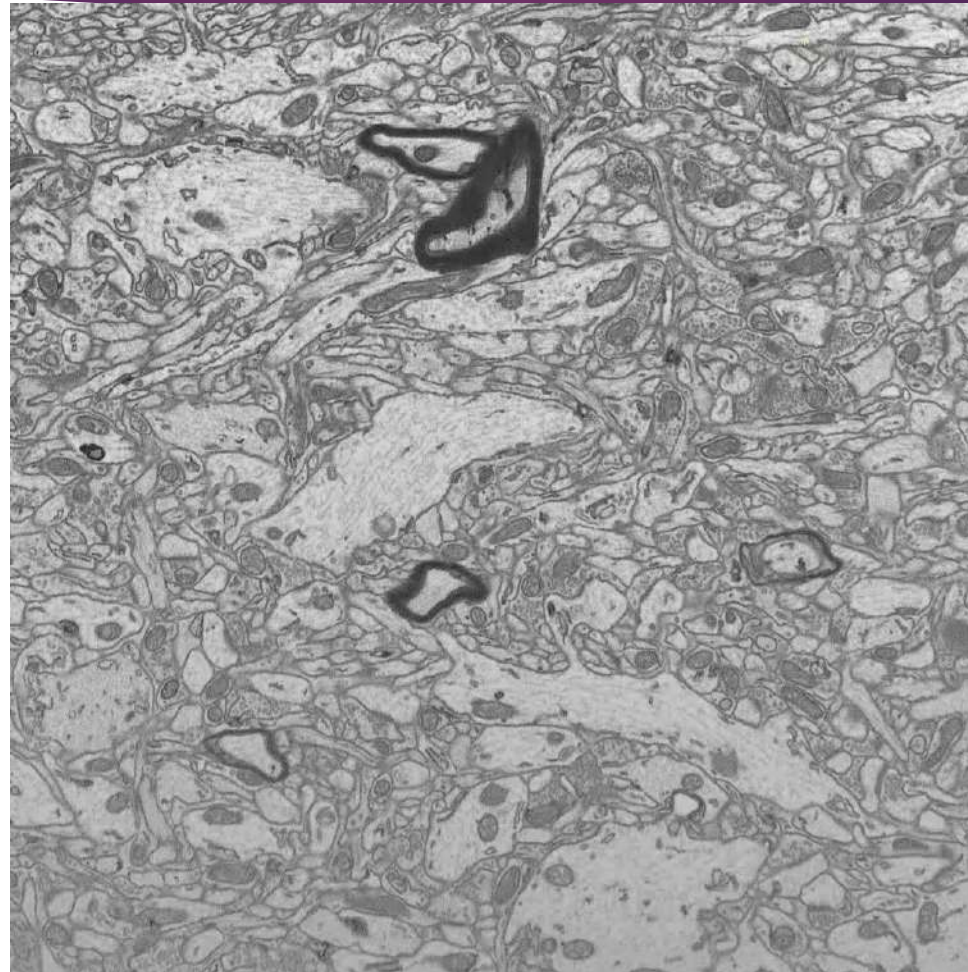
Application: 3D reconstruction of stained, resin-embedded tissue



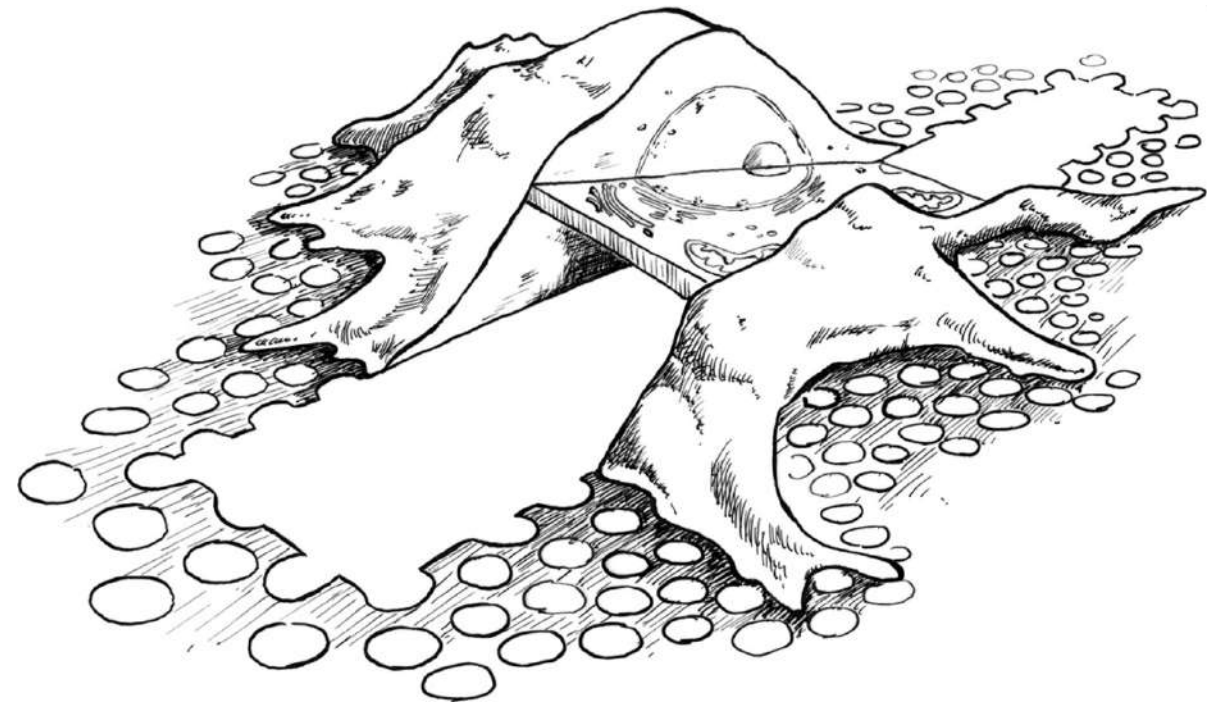
Milling: i-beam view



Example Movie: Neural Tissue

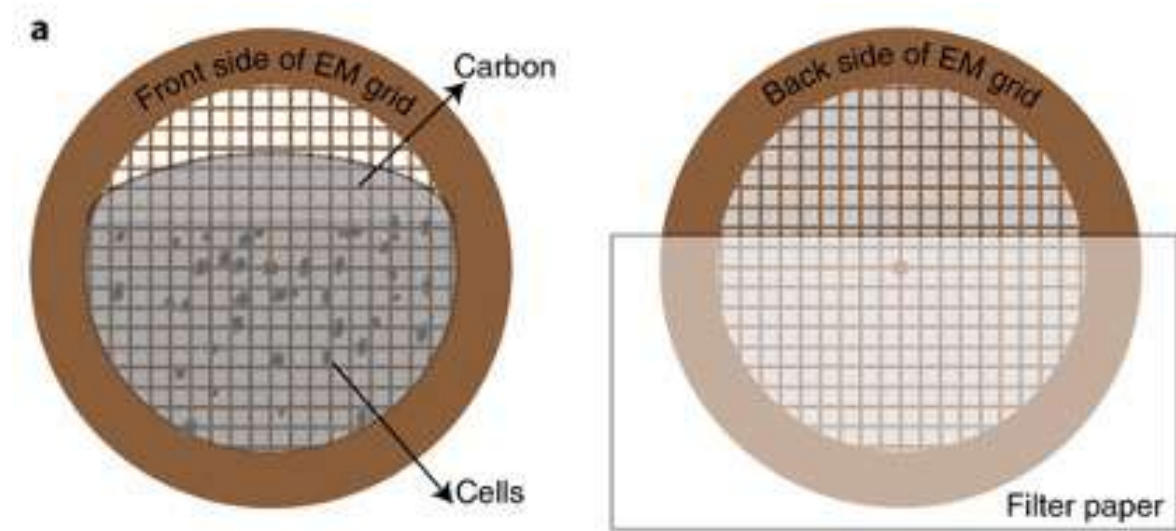


Cryo FIB/SEM for tomographic sample preparation



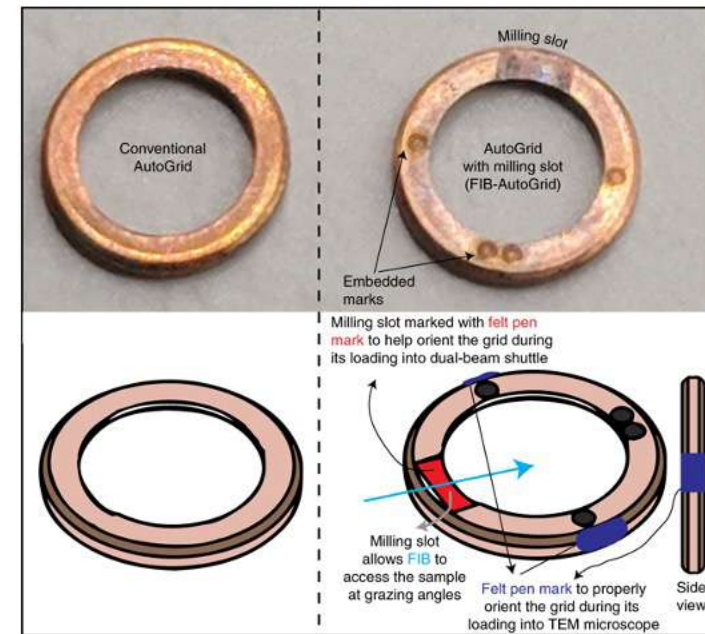
Place cells on Grids

- ▶ Need gold grids, not copper, for growing cells on grids
- ▶ Cells on carbon-facing side of grid
- ▶ If cells < 10 μm thick, plunge freezing should work
 - ▶ Back-blot to freeze grid
- ▶ For thicker specimens, a high pressure freezer is needed to vitrify



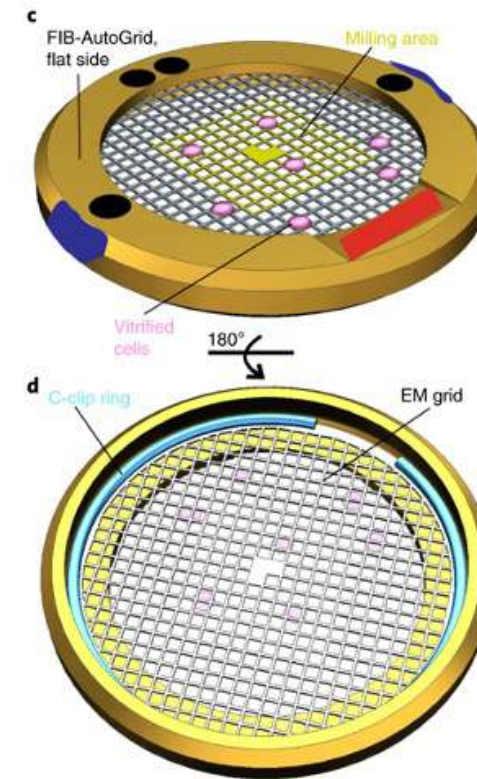
Grid Geometry

- ▶ After freezing, grids need to be clipped
 - ▶ Protection
 - ▶ Krios/Arctica
- ▶ Important to mark the autogrid!
- ▶ Autogrids with milling slot are commercially available
 - ▶ Milling slot allows lower angle of approach from ion beam



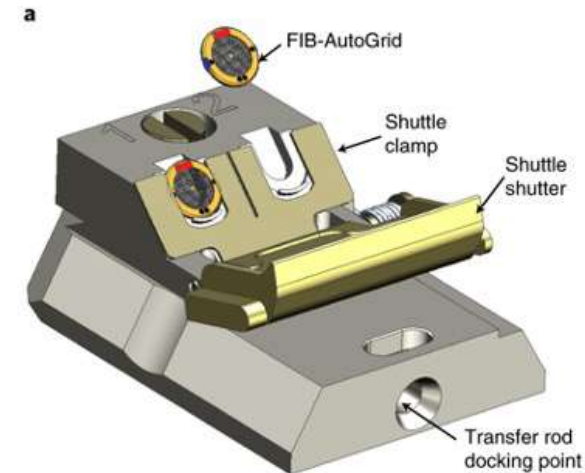
Grid Geometry

- ▶ Only the center of the grid is suitable for milling
- ▶ Cells are on flat-side of cartridge



Sample Shuttle

- ▶ Shuttle for loading grids into FIB SEM
- ▶ 2 grids at a time
- ▶ Geometry needs to be known
- ▶ Grids are pre-tilted 45°
- ▶ Shutter to protect grids



Transfer Rod for Loading

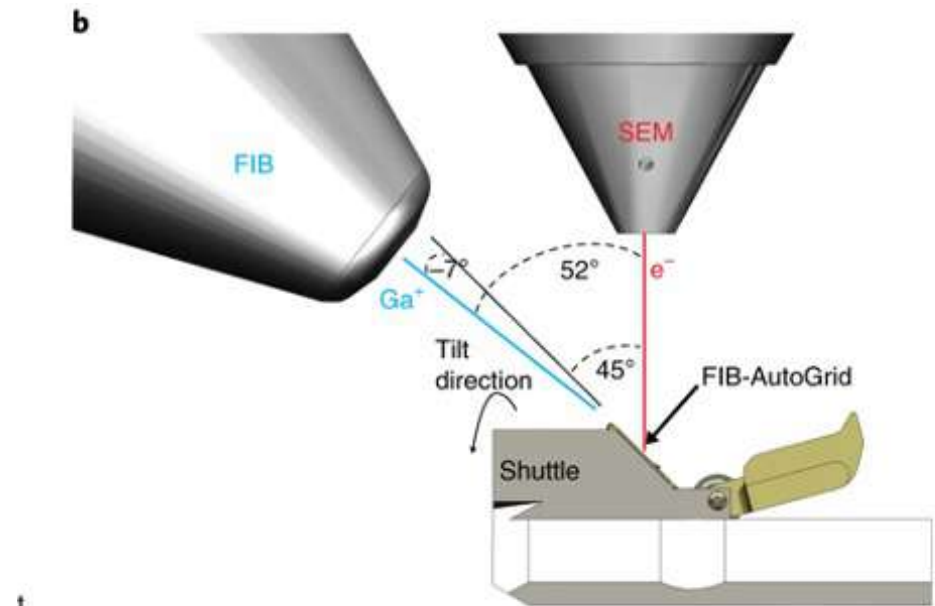


Older Loading Station (Quorum)



Geometry

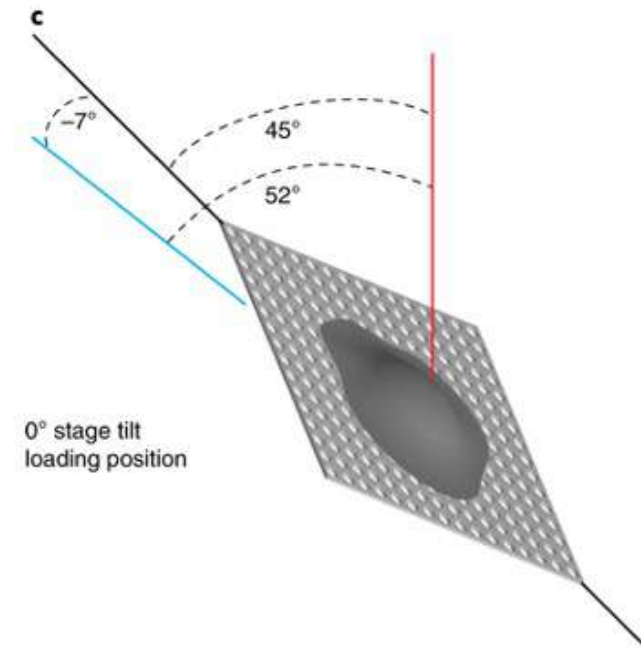
- ▶ Untilted stage:
 - ▶ Ga beam at -7° angle to grid surface
 - ▶ E-beam at 45° angle to grid surface



t

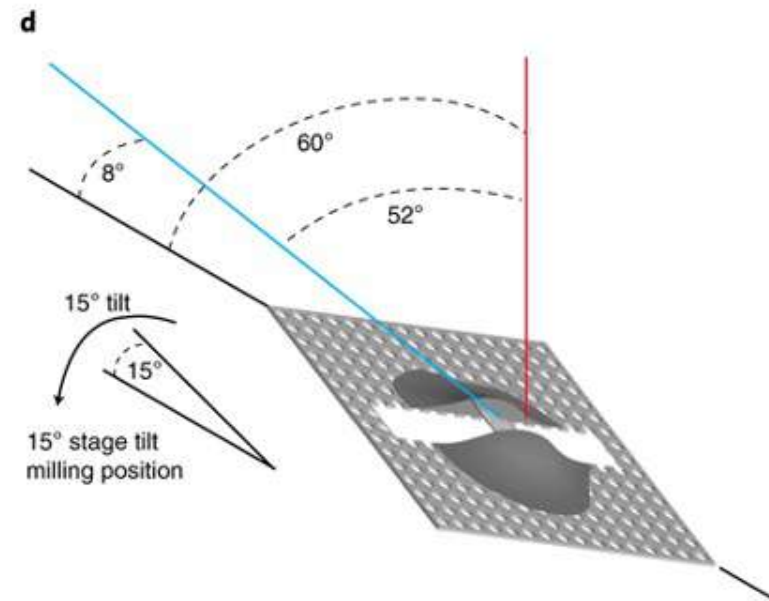
Geometry: Untilted

- ▶ Untilted stage:
 - ▶ Ga beam at -7° angle to grid surface
 - ▶ E-beam at 45° angle to grid surface



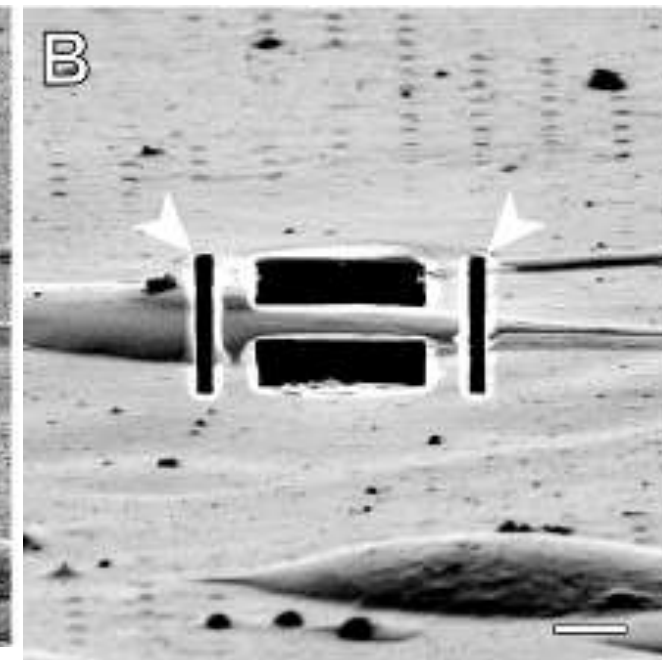
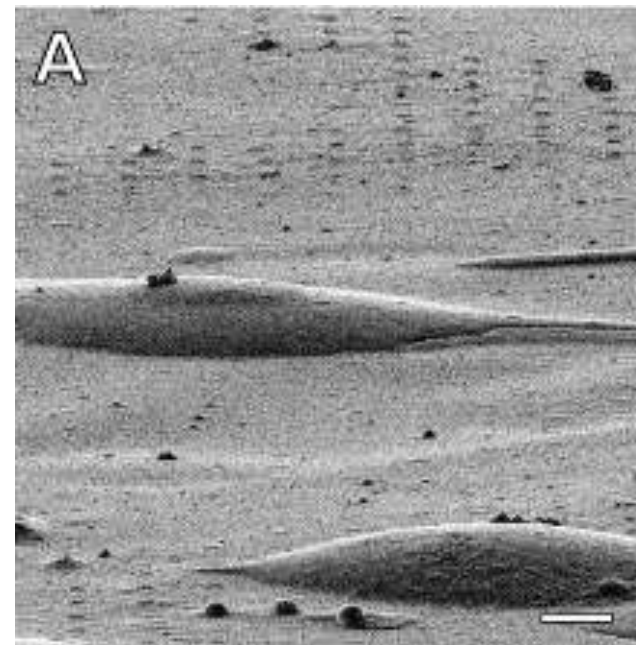
Geometry: Tilted

- ▶ Tilt stage +15°
 - ▶ Ga beam at +8° angle to grid surface
 - ▶ E-beam at 60° angle to grid surface

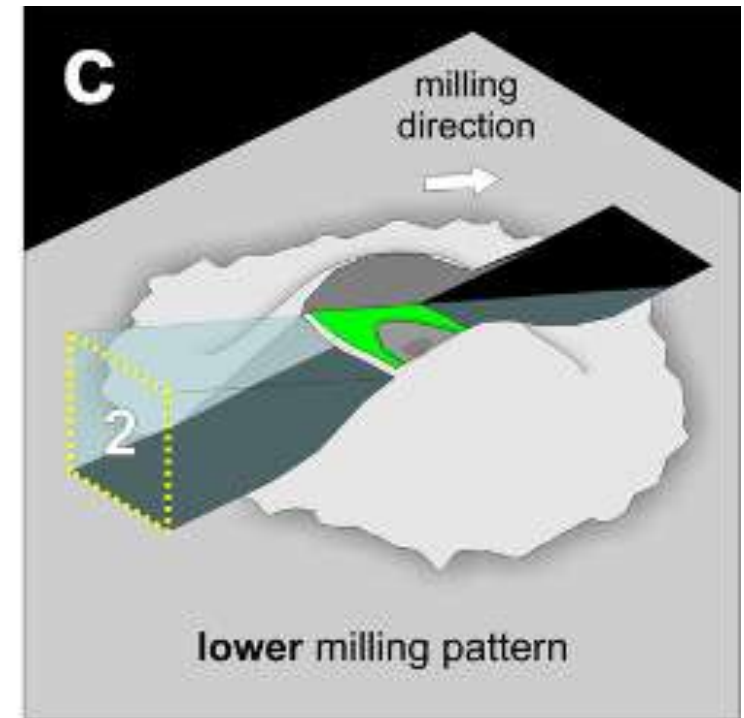
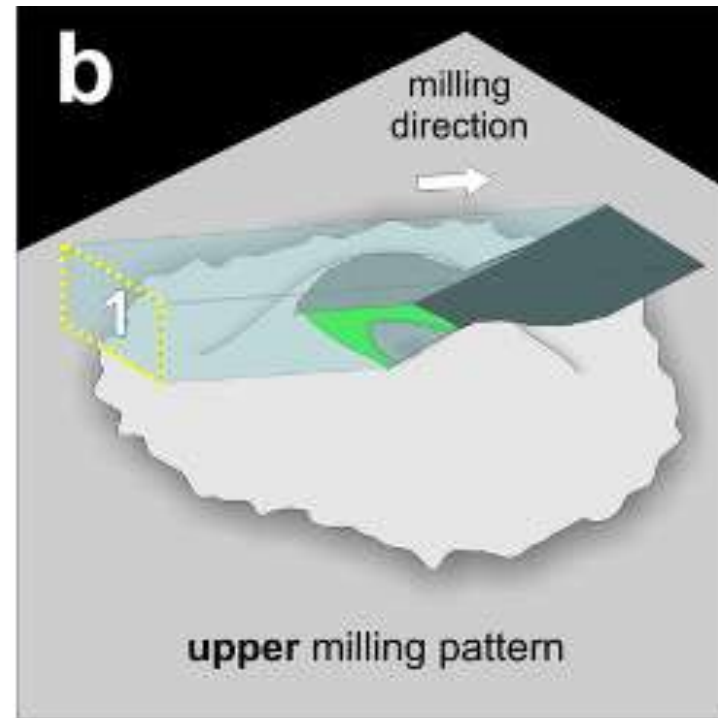
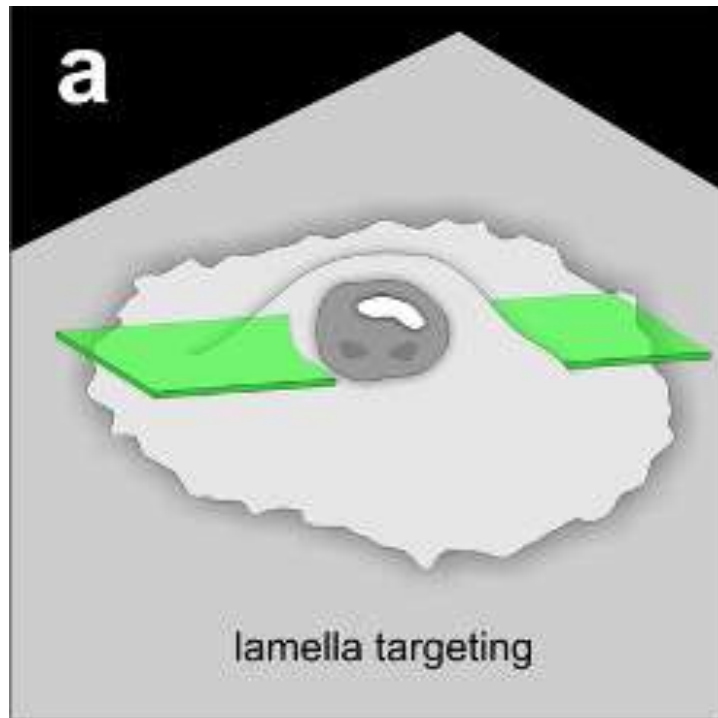


Imaging cells with ion beam

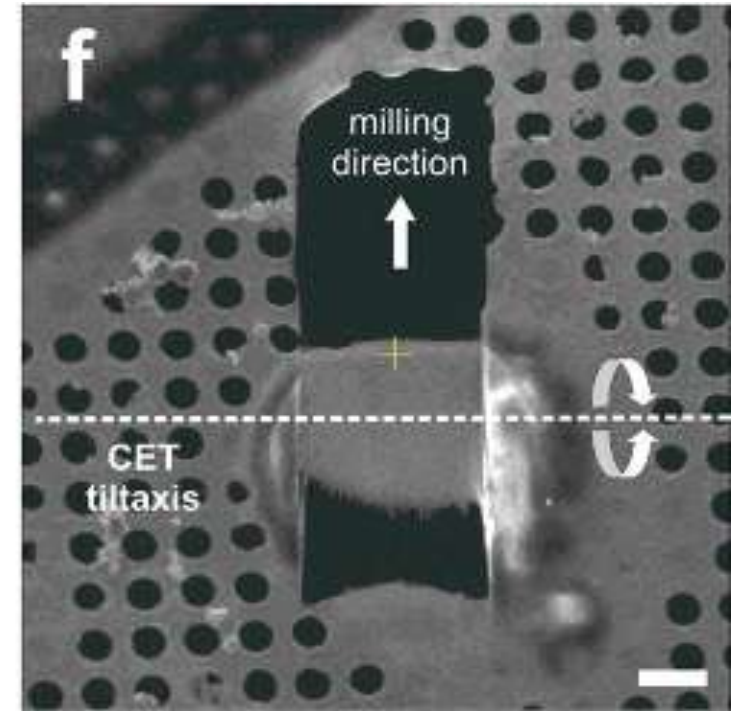
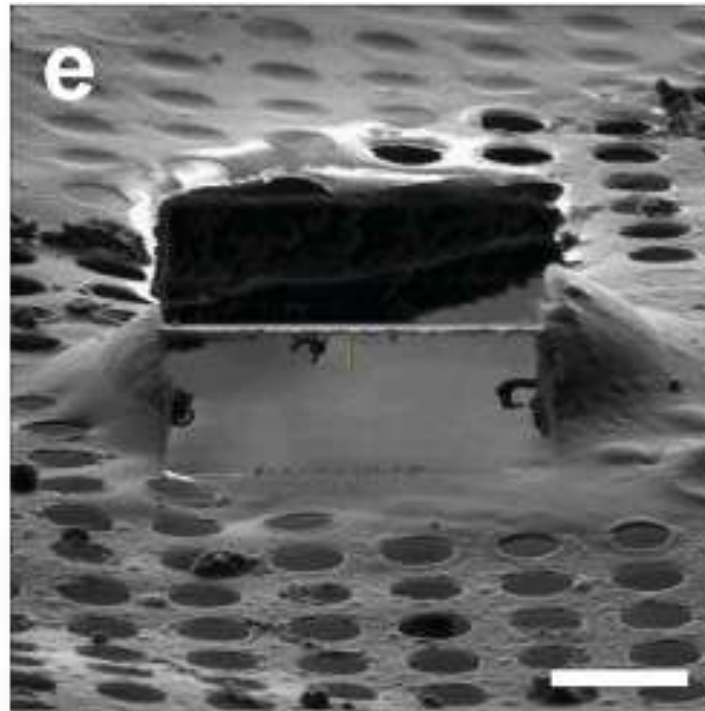
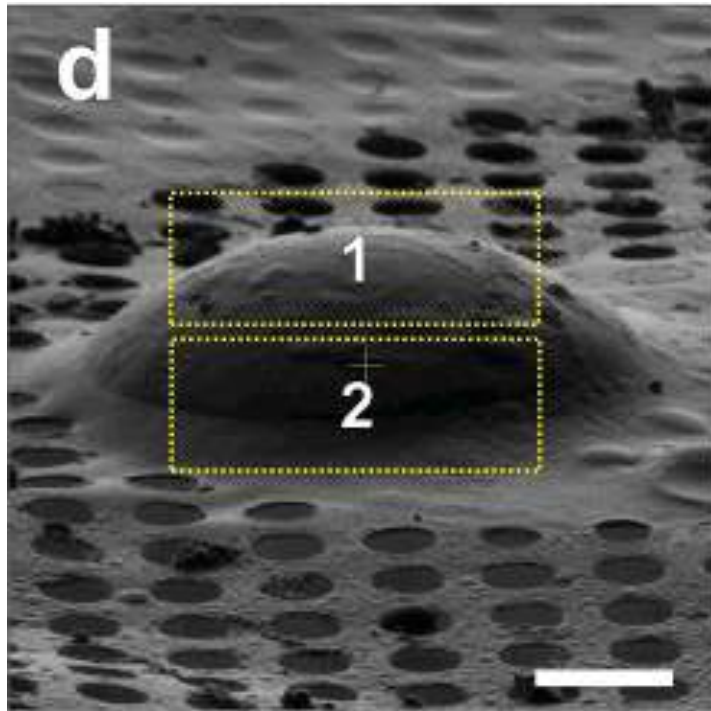
- ▶ A: Ion-beam view of cells
- ▶ B: Cells after milling, showing position of micro-expansion joints



Targeting of Milling Regions

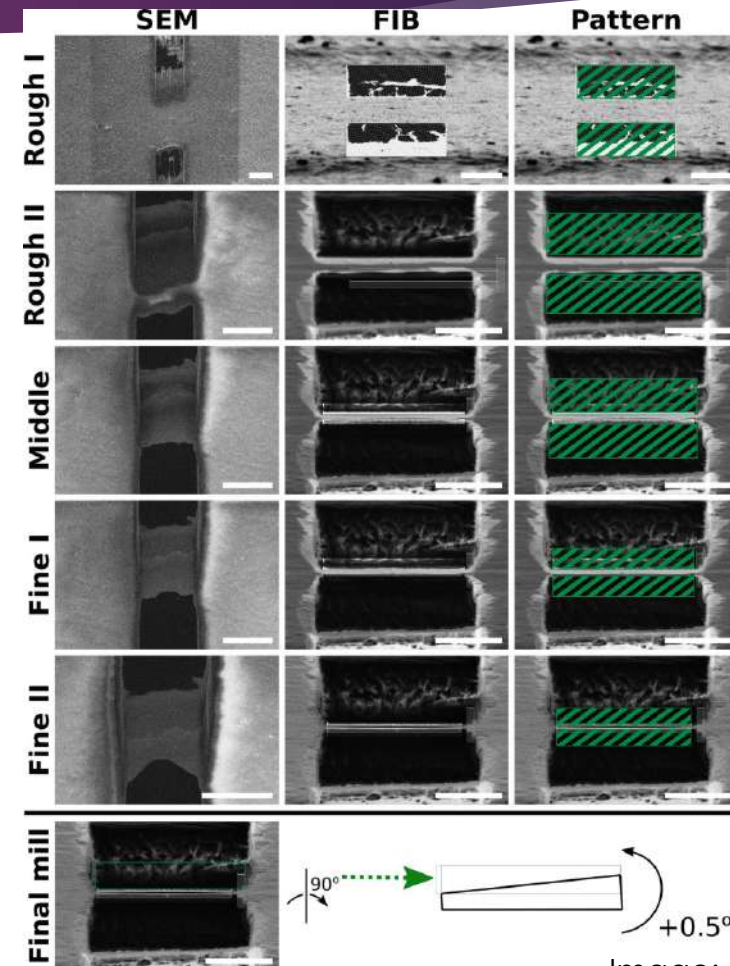


Targeting of Milling Regions

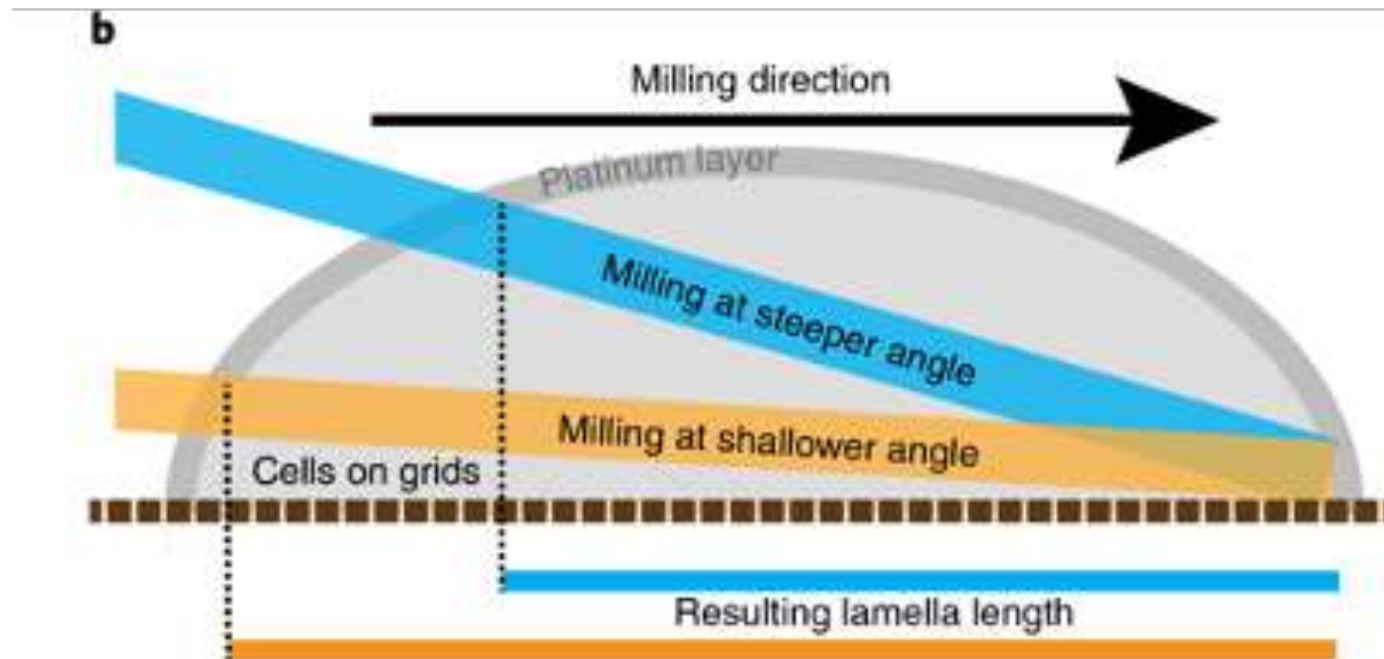


Milling

- ▶ In practice, milling is done in several steps
 - ▶ Rough cuts
 - ▶ Finer and finer polishing steps
 - ▶ Start at high current, finish at low current
 - ▶ Final step: additional 0.5° tilt to make lamellae even thickness throughout section
- ▶ Higher throughput
 - ▶ Target several regions and do rough mills
 - ▶ After all rough work is done, do final polishing and remove from SEM

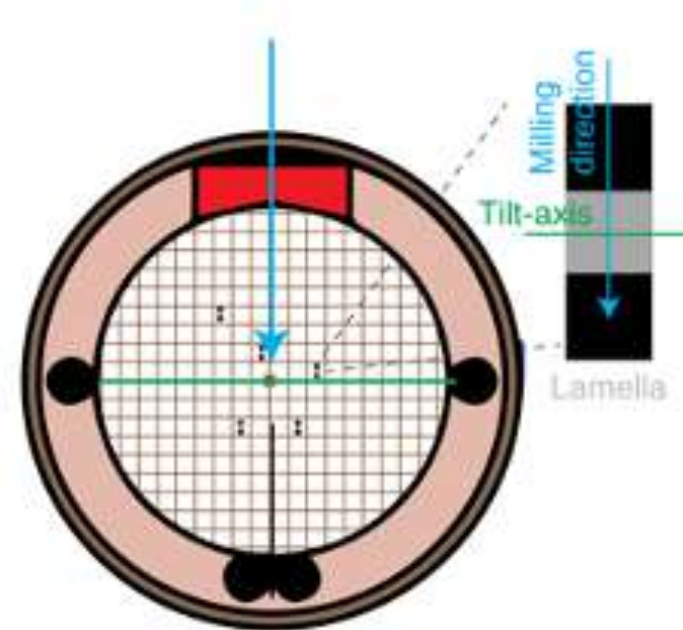


Milling at as shallow an angle as possible



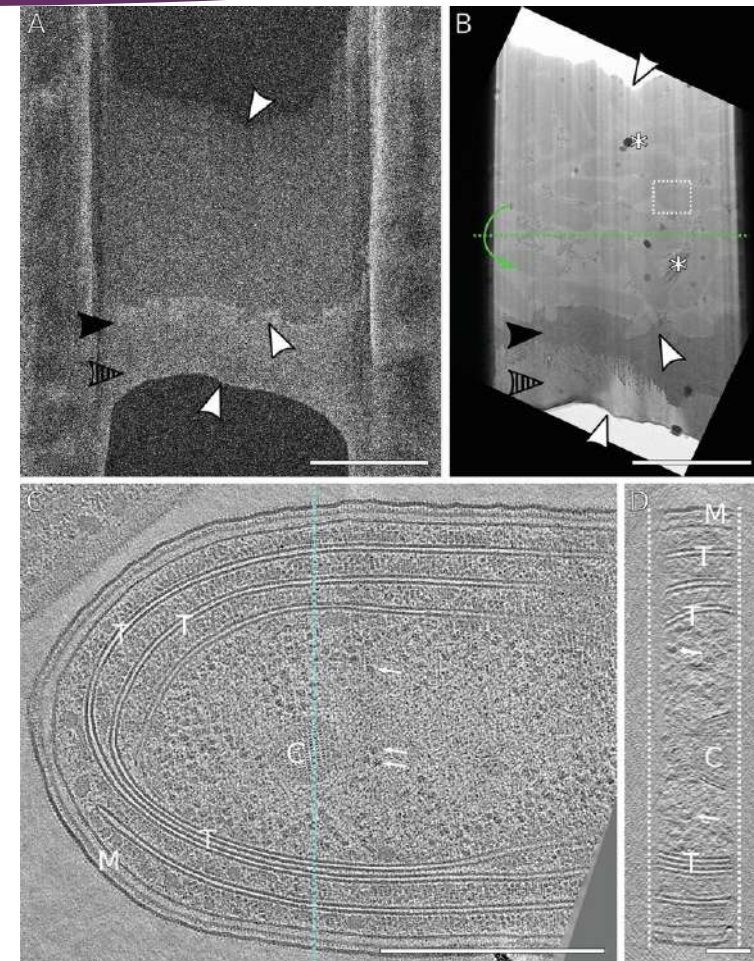
Geometry: Loading into TEM

- ▶ Sample needs to be loaded such that milling axis is perpendicular to microscope tilt axis



Ideal Result

- ▶ A: Image of prepared lamella using e-beam in FIB SEM
- ▶ B: Image of same region taken in Titan Krios. White arrows mark areas of correlation between (A) and (B). Solid black arrowhead: Pt from sputtering. Striped arrowhead: Pt from GIS. Green line shows the TEM tilt axis. White box: area for tilt-series acquisition. Asterisk: poor vitrification or contamination
- ▶ C: XY view of a reconstructed tomogram of a single cyanobacterium from the lamella.



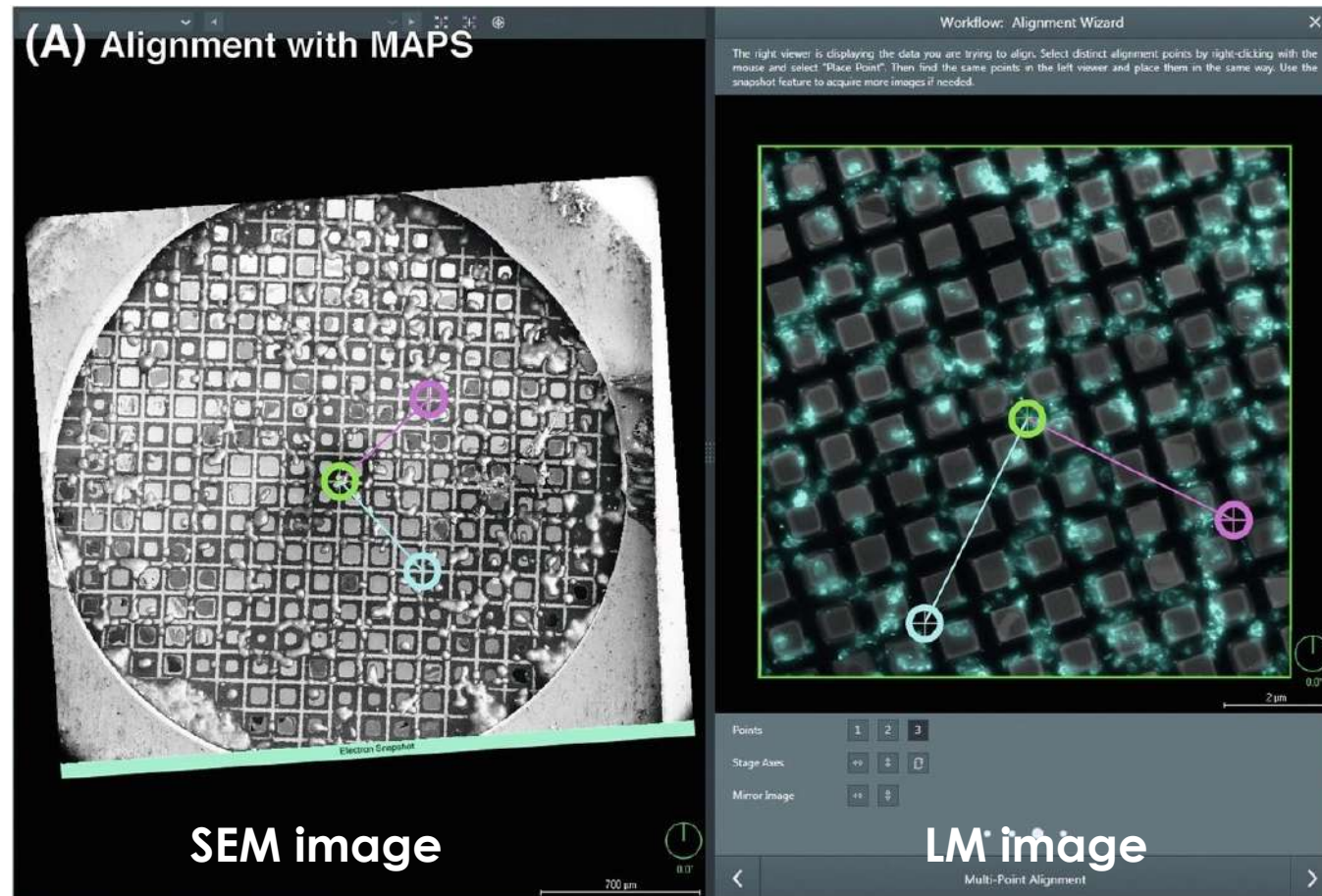
Difficulties / Issues

- ▶ Geometry: Need a cryo stage which will rotate and tilt with as much freedom as possible
- ▶ Sample Charging
 - ▶ Pre-coat with Pt Sputter coat
 - ▶ Perhaps post-coat with PT sputter as well
- ▶ Curtaining due to uneven milling
 - ▶ Cover with organic Pt layer to provide even surface
- ▶ Lamella Bending
 - ▶ Cut notches for stress relief
- ▶ All sample transfer steps have the danger of adding contamination

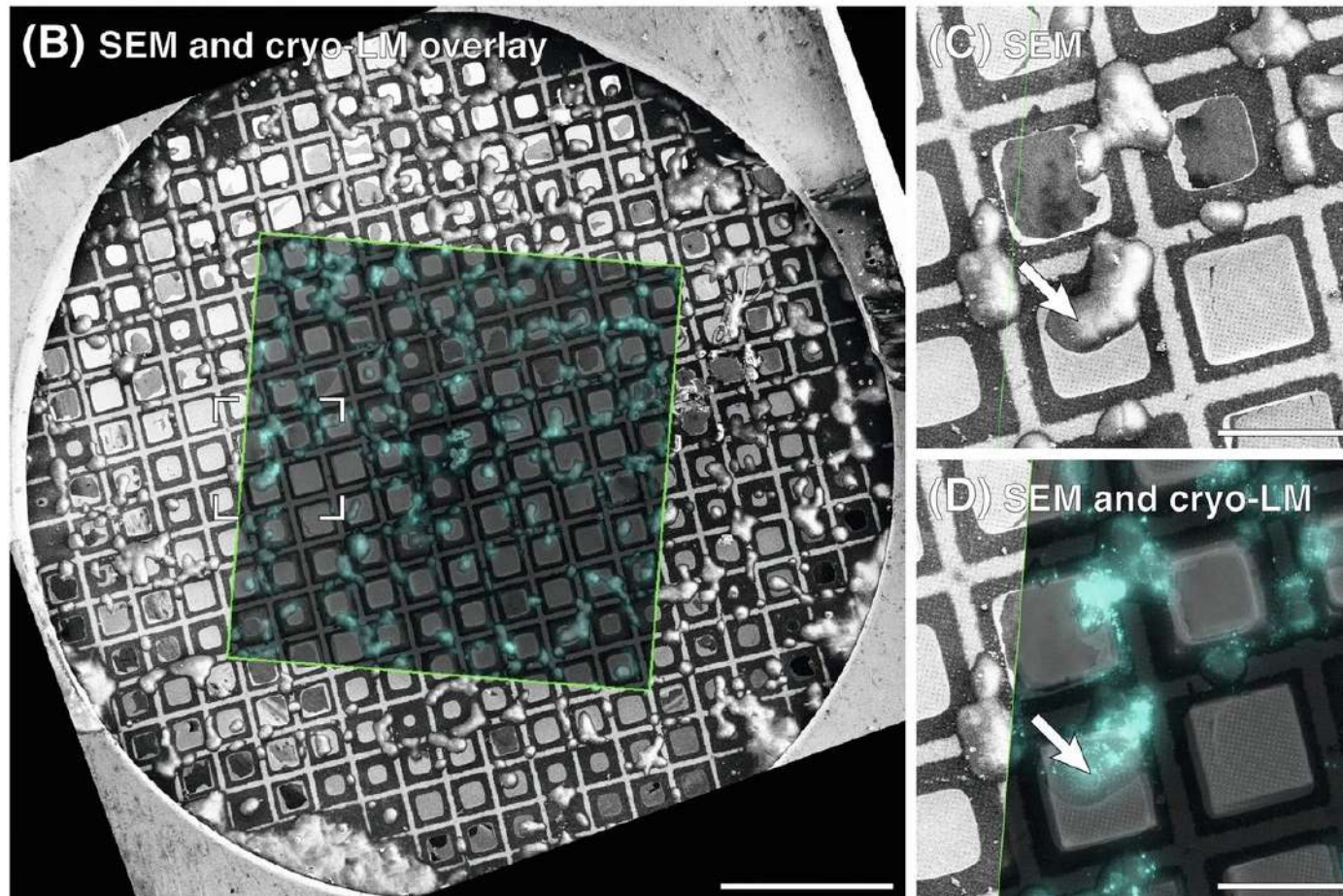
Where to mill?

- ▶ Unless all cells are the same, you need to be able to determine which are the target cells
- ▶ Also which part of the cell to keep
- ▶ Solution: Another microscope!
 - ▶ Fluorescent light microscopes with cryo stages are available
 - ▶ Need to have a long working distance, cannot use oil immersion, relatively high NA
 - ▶ Z signal is lowest resolution, confocal not available
 - ▶ Latest microscopes have software to import and correlate LM images with SEM images for localization
 - ▶ More transfers lead to increased danger of contamination / damage
 - ▶ Place LM inside SEM chamber?

Cryo-CLEM: Correlate points between images



Cryo-CLEM: Overlay



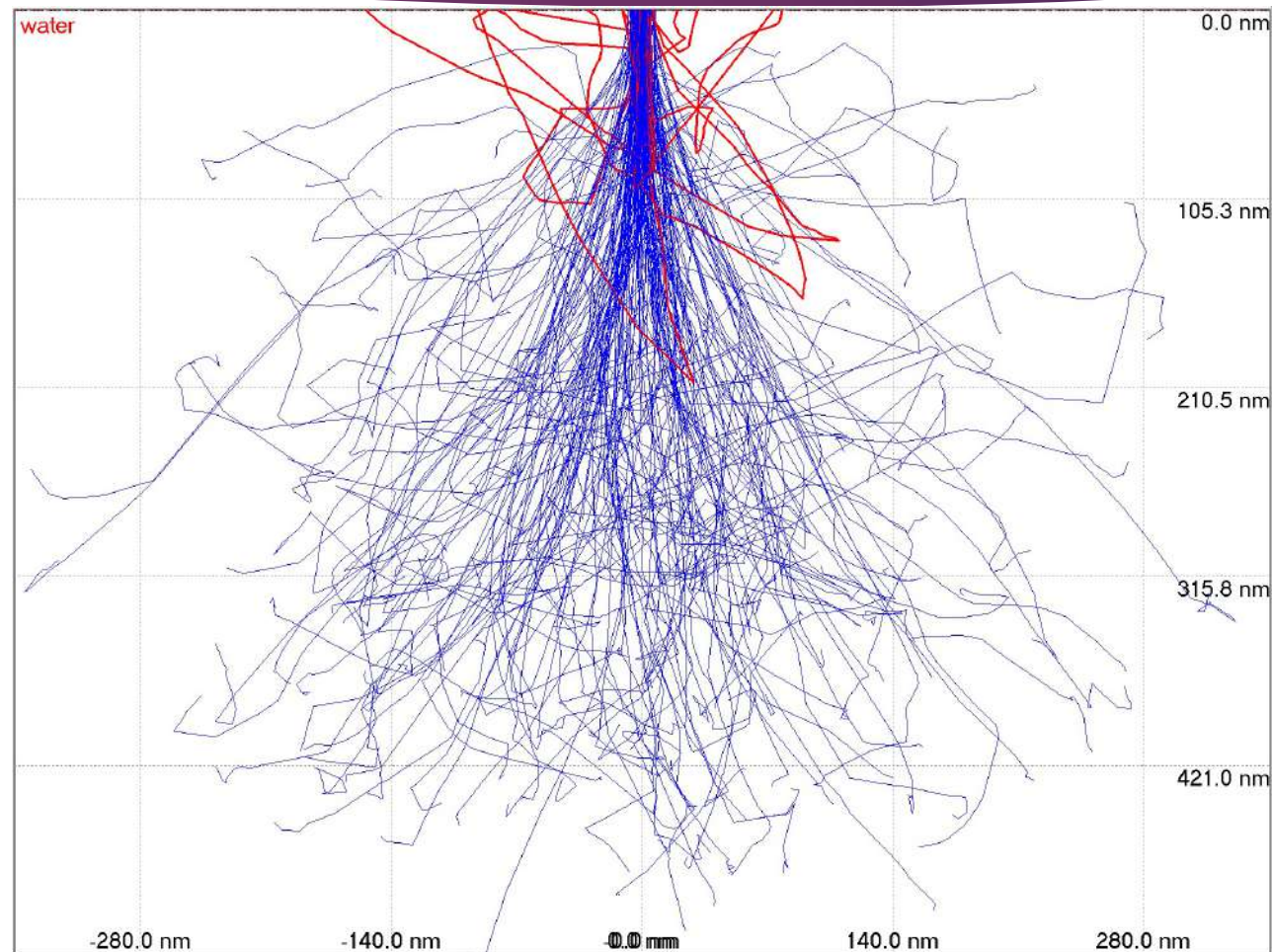
Summary: Equipment and expertise needed

- ▶ FIB SEM
 - ▶ Cryo stage with full rotation
 - ▶ GIS
 - ▶ Sputter coater
 - ▶ Shuttles and transfer equipment
 - ▶ Software for mapping and overlaying signals
- ▶ Cryo LM
 - ▶ Compatible cryo stage
 - ▶ Fluorescent signal detection
 - ▶ Shuttles and transfer equipment
- ▶ TEM
 - ▶ Suitable for high resolution tomography

References

- ▶ Buckley, G., G. Gervinskas, C. Taveneau, H. Venugopal, J. C. Whisstock and A. de Marco (2020). "Automated cryo-lamella preparation for high-throughput in-situ structural biology." J Struct Biol **210**(2): 107488.
- ▶ Goldstein, J. I., D. C. Joy, J. R. Michael, D. E. Newbury, N. W. M. Ritchie and J. H. J. Scott (2018). Scanning Electron Microscopy and X-Ray Microanalysis. New York, NY, Springer New York : Imprint: Springer,; 1 online resource (XXIII, 550 pages 546 illustrations, 409 illustrations in color.
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- ▶ Klein, S., M. Wachsmuth-Melm, S. L. Winter, A. Kolovou and P. Chlanda (2021). "Cryo-correlative light and electron microscopy workflow for cryo-focused ion beam milled adherent cells." Methods Cell Biol **162**: 273-302.
- ▶ Lam, V. and E. Villa (2021). "Practical Approaches for Cryo-FIB Milling and Applications for Cellular Cryo-Electron Tomography." Methods Mol Biol **2215**: 49-82.
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- ▶ Wagner, F. R., R. Watanabe, R. Schampers, D. Singh, H. Persoon, M. Schaffer, P. Fruhstorfer, J. Plitzko and E. Villa (2020). "Preparing samples from whole cells using focused-ion-beam milling for cryo-electron tomography." Nat Protoc **15**(6): 2041-2070.
- ▶ Wolff, G., R. Limpens, S. Zheng, E. J. Snijder, D. A. Agard, A. J. Koster and M. Barcena (2019). "Mind the gap: Micro-expansion joints drastically decrease the bending of FIB-milled cryo-lamellae." J Struct Biol **208**(3): 107389.

Monte Carlo simulation: water at 3 keV



Monte Carlo simulation: water at 5 keV

